

CHANGE NOTIFICATION

Analog Devices, Inc.
1630 McCarthy Blvd., Milpitas, CA 95035
(408) 432-1900

April 17, 2017

Dear Sir/Madam:

PCN#041717

Subject: Notification of Change in Moisture Sensitivity Level (MSL) Rating of the LTM4622 μ Module Regulator

This notice is to inform you that Analog Devices has downgraded the moisture sensitivity level (MSL) of the LTM4622 μ Module regulator to MSL4 (72hrs maximum floor life* out of the bag) from the original rating of MSL3 (168hrs maximum floor life out of the bag). There is no change to the peak reflow temperature.

Analog Devices conducted a more stringent MSL3 testing during the qualification of the LTM4622 than what is recommended by the IPC/JEDEC standard. However, because of the popularity of the LTM4622 and with its increasing production run rate, some recent production lots have shown a minor deviation from our internal MSL3 rating requirements. Therefore, as a precaution, MSL4 handling is advised and product shipments will be labeled as MSL4 according to JEDEC J-STD-020.

The list of part numbers affected:

LTM4622EV#PBF
LTM4622IV#PBF
LTM4622EY#PBF
LTM4622IY#PBF
LTM4622IY
LTM4622EY#3LFPBF
LTM4622EY#3LTPBF
LTM4622EV#3LLPBF
LTM4622EV#3KVPBF

This change is effective immediately. Should you have any further questions, please feel free to contact your local Analog Devices sales person or you may contact me at 408-432-1900 ext. 2077, or by E-mail JASON.HU@LINEAR.COM.

Sincerely,

Jason Hu
Quality Assurance Engineer

* Floor life: the allowable time period after removal from a moisture barrier bag, dry storage or dry bake and before the solder reflow process.

Sample Labels of MSL Rating



CAUTION

This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL
3

If Blank, see adjacent barcode label

1. Calculated shelf life in sealed bag: 24 months at < 40° C and < 90% relative humidity (RH).
If 24 months of shelf life is exceeded, follow instructions 4 below.
2. Peak package body temperature: 245 °C
If Blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must 168 hours of factory
a) Mounted within: 168 hours of factory
If Blank, see adjacent bar code label
conditions ≤ 30 °C/60% RH, OR
b) Stored at <10% RH.
4. Devices require bake, before mounting, if:
a) Humidity Indicator Card is >10% when read at 23±5 °C
b) 3a or 3b not met.
5. If baking is required, devices may be baked for
48 hours at 125±5° C.

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: MAR 01 2016
If Blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020



CAUTION

This bag contains
MOISTURE-SENSITIVE DEVICES

LEVEL
4

If Blank, see adjacent barcode label

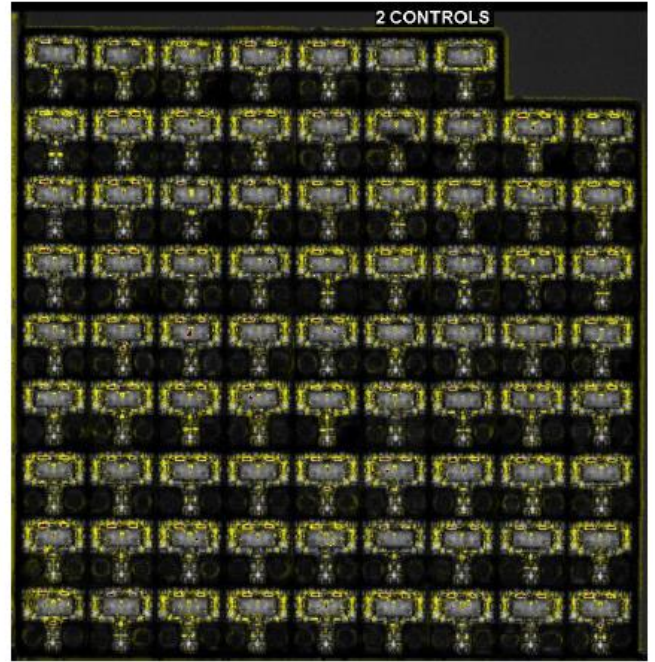
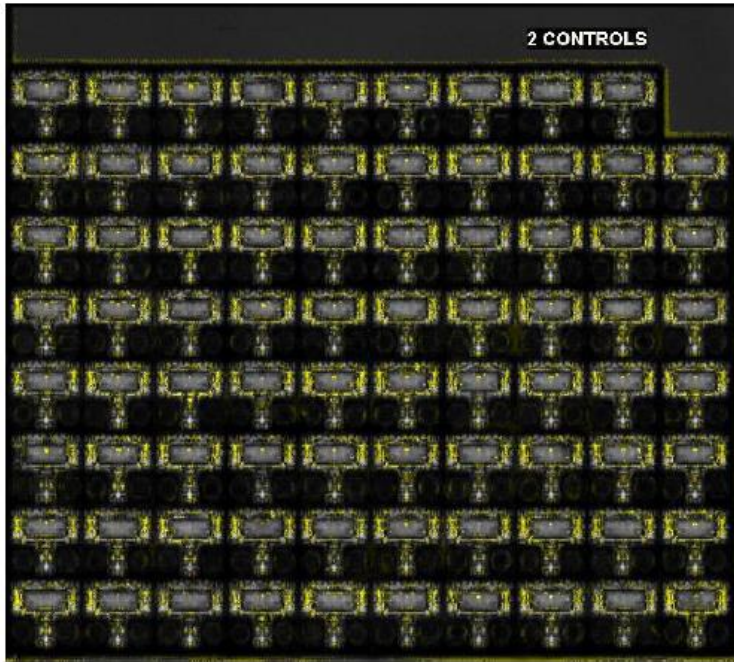
1. Calculated shelf life in sealed bag: 24 months at < 40° C and < 90% relative humidity (RH).
If 24 months of shelf life is exceeded, follow instructions 4 below.
2. Peak package body temperature: 245 °C
If Blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must 72 hours of factory
a) Mounted within: 72 hours of factory
If Blank, see adjacent bar code label
conditions ≤ 30 °C/60% RH, OR
b) Stored at <10% RH.
4. Devices require bake, before mounting, if:
a) Humidity Indicator Card is >10% when read at 23±5 °C
b) 3a or 3b not met.
5. If baking is required, devices may be baked for
48 hours at 125±5° C.

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: 3-30-17
If Blank, see adjacent bar code label

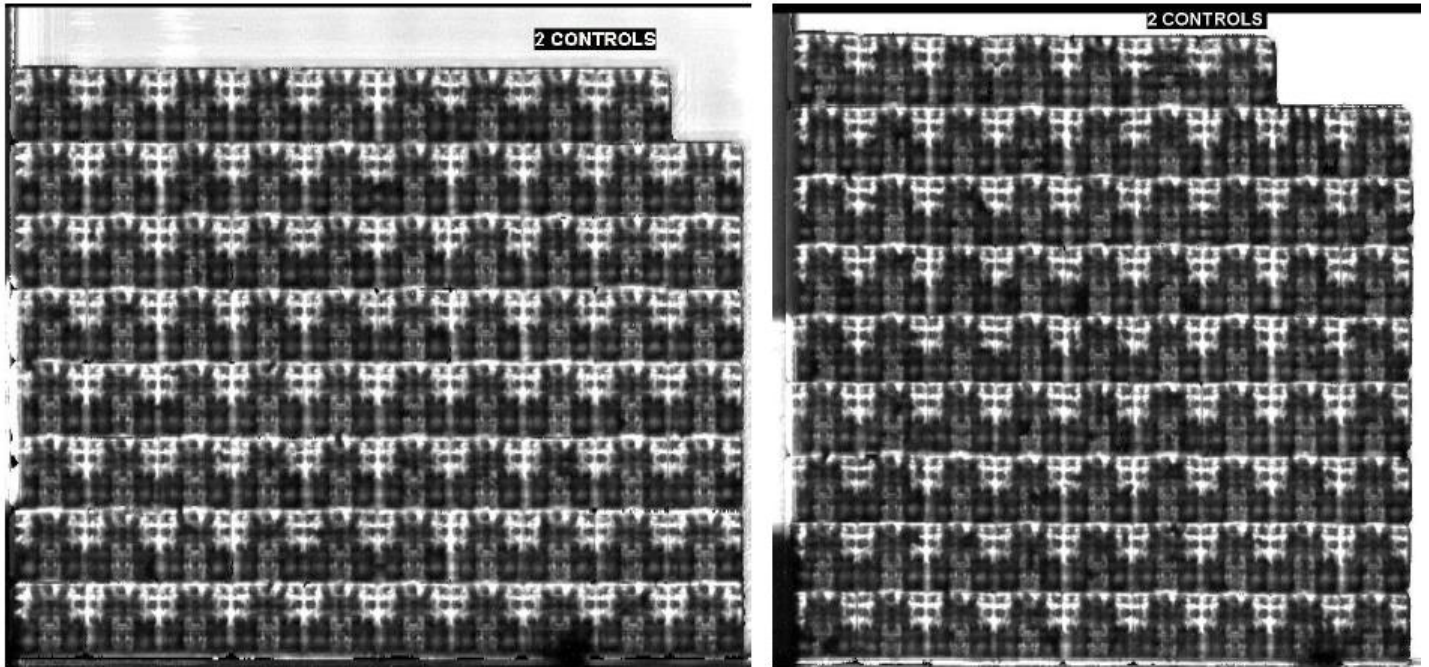
Note: Level and body temperature defined by IPC/JEDEC J-STD-020

C-SAM Inspection



Pre (left) and Post (right) MSL 4 Preconditioning C-SAM images

C-SAM Inspection



Pre (left) and Post (right) MSL 4 Preconditioning Thru-Scan images